Multi-physics design optimization of a GaN based   
integrated modular motor drive system

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**Keywords:** integrated motor drive, modular motor, permanent magnet synchronous machine, Gallium Nitride, interleaving

Abstract

In this paper, a multi-physics approach is presented for the design optimization of an integrated modular motor drive (IMMD). The system is composed of a modular permanent magnet synchronous motor and a GaN based modular motor drive power stage. The multi-physics model includes motor drive inverters and DC link capacitor bank (electrical model), stator windings and rotor magnets (electromagnetic model), heat sink (thermal model) and a geometrical model. The main purpose of the design optimization is to obtain the highest power density possible, which is quite critical in integrated drives. Due to the integrated structure, the system has several interdependencies and parameters are selected based on those relationships. An 8 kW IMMD system design is proposed and the resultant system design is verified using various simulation platforms.

1 Introduction

Conventional variable frequency motor drives are composed of two distinct parts: drive and motor, where the drive unit(s) are placed in separate cabinets and connected to the corresponding motors with long cables. This reduces the power density, increases cost and causes electromagnetic interference (EMI) problems [1]. In integrated modular motor drive (IMMD) systems, the drive is integrated onto the motor back iron forming a single package such that the power density of the overall system is increased and the connection cables are eliminated [1]. Furthermore, each pole of the motor is driven by its own drive module which are then interconnected via a common DC link. By doing so, the fault tolerance of the system is increased, heat dissipation is spread on a wider surface area and voltage stress on windings and power semiconductor devices are reduced [2].

In IMMDs, the space available for the drive system components is drastically reduced due to integration. Therefore, fitting all the components requires design optimization with integrated model approach and careful spatial and layout design. Moreover, the interdependencies between the main system components yields a multi-physics approach where the design of motor, drive power electronics and thermal management system should be considered all together. Therefore, it is highly difficult to propose a decoupled design approach in integrated drives as one parameter may affect the other significantly [3].

The current IMMD prototypes proposed in the literature are usually based on the new generation wide band-gap power semiconductor devices, such as Gallium Nitride (GaN) power FETs [4]. These devices are capable of switching at much higher switching frequencies compared to their silicon counterparts thanks to their low switching losses [5]. It is possible to reduce the size of passive components with high switching frequencies as well as reduce the size of heat sink with superior efficiency values with the utilization of enhancement mode (e-mode) GaNs. Considering that the largest components on an average power converter system are passive components and the heat sink [1], utilization of these devices is critical for IMMD designs. Moreover, thanks to the modularity of the system, interleaving technique can be used to further reduce the size of DC link capacitor bank [6]. Although several studies have been published regarding power electronics design, modular inverter topologies, DC link capacitor selection etc. for IMMDs [1,3,7,8], most of these prototypes lack a unified design procedure. One example for such a dependency is that, the cross-sectional area available for the motor drive printed circuit board (PCB) and heat sink is determined by the diameter of the motor.

In this paper, the optimum design of a 8kW IMMD system is presented considering both the motor and drive parameters to obtain the highest power density. It is also aimed to maximize the overall system efficiency while keeping the active material costs in acceptable limits. A permanent magnet synchronous motor (PMSM) having fractional slot concentrated winding (FSCW) stator is utilized for its superior torque density and fault tolerance capability which makes it suitable for IMMD applications [9]. The content of the multi-physics design optimization approach includes electrical, electromagnetic, thermal and geometrical models. First, the multi-physics model is presented in Section 2. In section 3, the basic relations between the system parameters and the cost and constraint functions are obtained and the inter-dependencies are discussed. Using the results of Section 3, an optimum system design is proposed in Section 3. In Section 4, the presented models are verified and the proposed system design is evaluated using simulation results. The paper is concluded in Section 5.

2 System modelling

Motor drive integration onto the modular stator back iron is considered in this paper, an example of which is shown in Fig. 1 [7]. The structural configuration of the proposed system is also shown in Fig. 2.

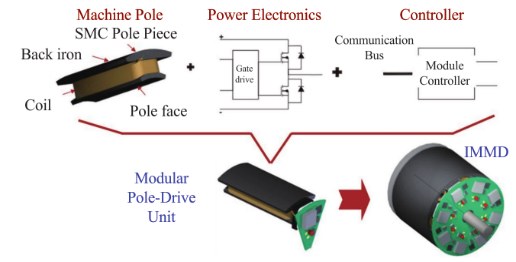


Figure 1. An example of the IMMD structure [7]



Figure 2. Structural configuration of the proposed IMMD

The main blocks of the system model and the relations between different aspects used in the integrated design are shown in Fig. 3. Basically, the system is composed of the electrical model, electromagnetic model, thermal model and geometrical (spatial) model. The system specifications and constraints are listed in Table 1. Moreover, the independent variables and their corresponding sub-models are also shown in Table 2. The IMMD system has a modular structure where each three-phase inverter module drives its own part of the stator pole. The modules can be connected in series and/or parallel configuration via a common DC link. A block diagram of the system is shown in Fig. 3 with 2-series and 2-parallel connected modules.



Figure 3. Main blocks of the system model

|  |  |
| --- | --- |
| **Parameter** | **Value** |
| DC link voltage, *Vdc* | 540 V |
| Number of phases in each module, *m* | 3 |
| Motor total output power, *Pout* | 8 kW |
| Motor rated speed, *Nr* | 600 rpm |
| Machine electric loading, *Arms* | 35 kA/m |
| Machine magnetic loading, *Bavg* | 0.6 T |
| Maximum winding current density, *Jrms* | 4 A/mm2 |
| Maximum stator teeth flux density, *Bts* | 1.8 T |
| Maximum stator yoke flux density, *Bys* | 1.4 T |
| Maximum fill factor, *kcu* | 0.6 |
| Maximum device junction temperature, *Tj-max* | 150 0C |
| Maximum capacitor temperature, *Tcap-max* | 70 0C |
| Maximum DC link voltage ripple, *Vdc-r* | 1 % |
| Minimum motor efficiency, *ηm-min* | 94 % |
| Minimum drive efficiency, *ηd-min* | 98 % |
| Minimum power factor, *cos(φ)min* | 0.9 |
| Ambient temperature, *Tamb* | 50 0C |

Table 1. System specifications and constraints

|  |  |
| --- | --- |
| **Optimization parameters** | **Sub-model** |
| Number of modules, *n* | *Electrical* |
| Number of series modules, *ns* | *Electrical* |
| Switching frequency, *fsw* | *Electrical* |
| Modulation index, *ma* | *Electrical* |
| Aspect ratio of the motor, *α* | *Geometrical* |
| Slot/module/phase, *ws* | *Electromagnetic* |

Table 2. Optimization parameters (independent variables)



Figure 3. A general block diagram of the IMMD

2.1 Electrical sub-model

The electrical model selects rated parameters of the motor drive inverter, power semiconductor devices, calculates motor drive losses and required DC link capacitor parameters. A set of 650V e-mode GaN FETs suitable for high voltage applications having different current ratings from GaN systems are used for the design [ref]. The devices are selected from these commercial products based on the number of series and parallel modules (*ns, np*), modulation index (*ma*), power factor (*cos(φ)min*) and motor efficiency (*ηm-min*) limitations. By using the selected device parameters, the motor drive losses are determined as shown in (1) for forward conduction loss, (2) for reverse conduction loss, (3) for switching loss, where *Eon*, *Eoff* and *Eoss* are the on state, off state and output capacitance switching energies, respectively, *Rds-on* is the on state resistance, *Ip* is the peak line current.

|  |  |
| --- | --- |
|  | (1) |
|  | (2) |
|  | (3) |

The analytical models for the determination of required capacitance (*Cdc*) and RMS current rating (*Ic-rms*) for a typical inverter are given in (4) and (5), where *Irms* is the rms line current [ref]. For a modular motor drive, it is possible to use interleaving technique to reduce these requirements. The effect of interleaving is determined by proper phase shifting angle for each possible case and added to the capacitance and ripple current requirements. It has been shown that series connection has no effect on the ripple current and ripple voltage for any phase shifting angle. The normalized effect of interleaving on these parameters is shown in Fig. 5.

|  |  |  |
| --- | --- | --- |
|  | (4) |  |
|  | (5) |  |



Figure 5. The effect of interleaving for parallel connected modules

A database of film capacitors are used from commercial products [ref] for capacitor selection model which is based on the capacitance, ripple current and DC voltage requirements. The selected capacitor is checked whether its core temperature exceeds the specified limit or not, by using the implicit thermal model expressed in [ref] and capacitor datasheet values such as ESR, thermal conductance etc. Temperature dependency is especially critical since it affects the lifetime of the capacitors significantly. The required phase induced voltage per module (*Ephm*), which is the link between the electrical and electromagnetic models is determined using the inverter model as in (6).

|  |  |
| --- | --- |
|  | (6) |

2.2 Electromagnetic sub-model

This section summarized the electromagnetic design of a PMSM for the IMMD application. The number of stator slots (*Qs*) is determined by using *ws, m* and *n*. The machine stator structure is FSCW as it is more suitable for high torque modular motor applications thanks to its high power density and torque density, low cogging torque, low manufacturing cost and fault tolerance capability. The number of poles (*p*) is determined for each possible *Qs* to get low cogging torque while keeping the winding factor high enough and harmonic content at minimum. Tables with pre-determined winding factor values (*kw*) for different *Qs*/*p* combinations are used for winding factor [ref].

The air gap distance (*lg*) is found using the target peak air gap flux density (*Bgp*) and the properties of the selected magnet (*NeFeB*) as in (7), using the lumped parameter magnetic circuit model shown in Fig. 6, where *lm* is the magnet length. The same methodology is used for the determination of tooth width (*bt*) and back core height (*hbc*) using the maximum allowable flux density (*Bts-max*and *Bys-max*), as in (8) and (9), where *em* is the magnet embrace and *Dis* is the bore diameter.

(a) (b)

Figure 6. (a) Electromagnetic lumped parameter magnetic circuit, (b) Slot dimensions

|  |  |
| --- | --- |
|  | (7) |
|  | (8) |
|  | (9) |

The determination of the number of turns is based on *Ephm* and flux per pole (*Φpp*). *Φpp* is found using pole area and flux density. Induced voltage on one turn is determined as in (10), where *La* is the axial length and *fr* is the mechanical frequency. The number of turns per coil side (*Ncs*) can be found using (11), where *l* is the number of layers. The phase current of each module is found by assuming that the motor is operated in vector control mode where the induced voltage is always in-phase with the current, as in (12). The electric loading of the machine is verified using the rated phase current as in (13). Once the rated current is established, winding is selected from standard AWG wires with the specified current density limit (*Jrms*). The only remaining parameter on the machine dimensions is the slot height (*hs2*) as shown in Fig. 6. The limiting factor for *hs2* is the maximum slot fill factor (*kcu-max*), as seen in (14). Now, all the dimensions of the machine are set including the stator outer diameter (*Dos*) which is critical for power density.

|  |  |
| --- | --- |
|  | (10) |
|  | (11) |
|  | (12) |
|  | (13) |
|  | (14) |

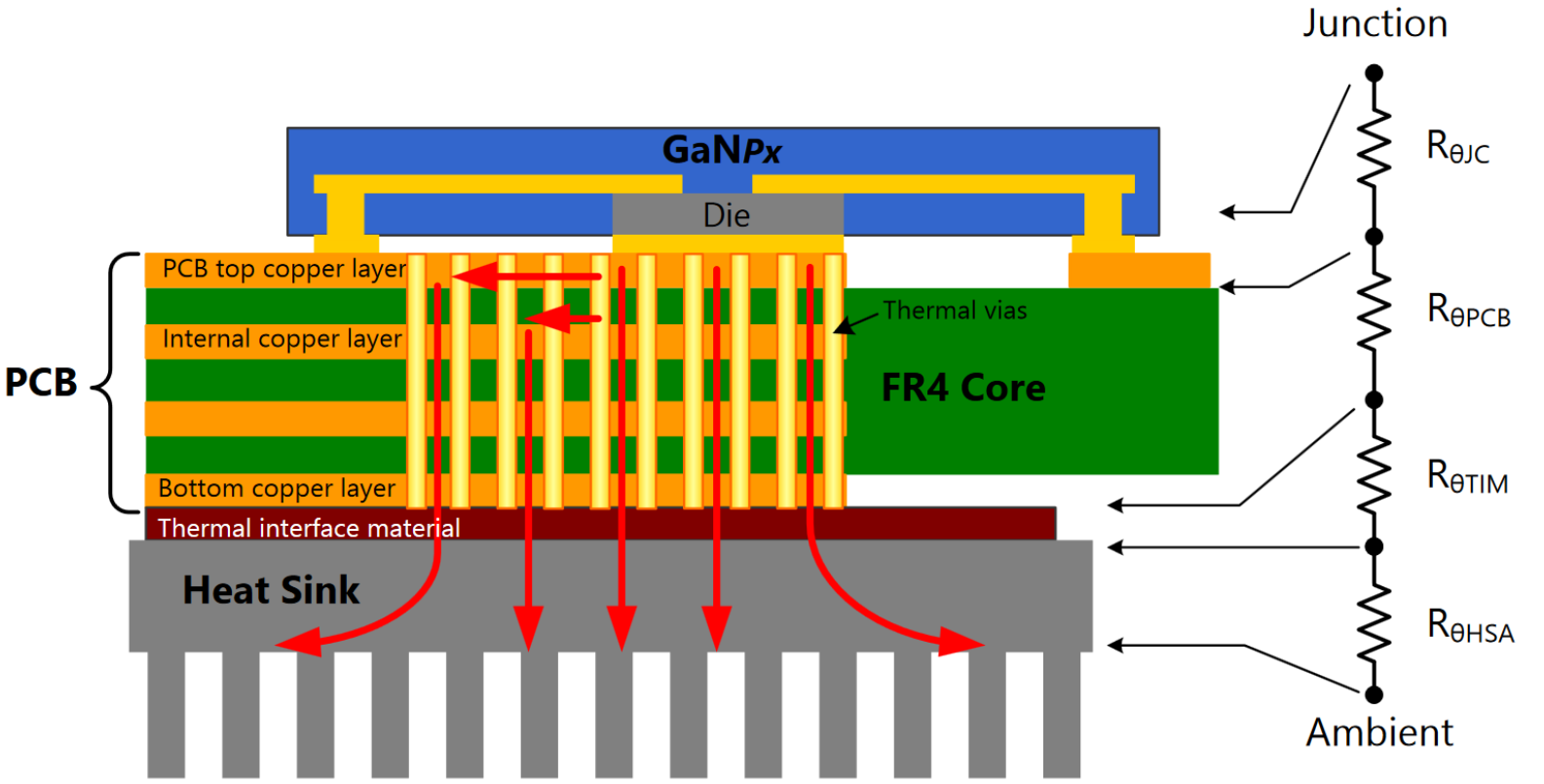
Once all the machine dimensions, winding configuration and turn numbers are set, the machine losses are calculated for the evaluation of the design. Copper loss is directly related to the selected winding cross-section (*Awdg*) and the mean-length-turn as expressed in (15). The temperature effect is added via the temperature coefficient of copper, where *ρcu* is the resistivity of copper for a given temperature. For core loss, the selected lamination (*M250-50A*) is used in several FEA simulations to determine the core loss density with worst case flux density values in several parts of the core. A core loss density of *4 W/kg* is obtained including fundamental and harmonic components and used for core loss calculation.

|  |  |
| --- | --- |
|  | (15) |

2.3 Thermal sub-model

The structure of the thermal model with the selected GaN devices and its lumped parameter thermal circuit used at steady state to determine the maximum heat sink thermal resistance (*Rth-sa*) are shown in Fig. 7. Natural cooling is considered in the design due to the reliability issues. The calculation of *Rth-sa* is expressed in (17) to ensure that the junction temperature of any device does not exceed its maximum value (*Tjmax*). Thermal resistance of PCB and thermal interface material (TIM) are determined using manufacturer’s application note [10]. Analytical models are used for heat sink, as the heat sink structure and range of size and fin geometry are established. The fin geometry and physical model of the heat sink is shown in Fig. 8. The thermal resistance of the heat sink is expressed in (18) for natural convection, where *Abase* is the base plate area, *Afin* is the total fin surface area, *ηfin* is the fin efficiency and *Nfin* is number of fins. The convection coefficient (*h*) is found using an analytical model derived by zzzz in [xx].





(a) (b)

Figure 7. (a) Thermal model structure [10], (b) Lumped parameter thermal equivalent circuit

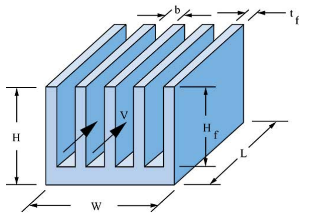


Figure 8. The physical model of the heat sink[11]

|  |  |
| --- | --- |
|  | (17) |
|  | (18) |

2.4 Geometrical sub-model

In the geometrical model, the main machine dimensions (*Dis, La*) are determined using torque per unit volume, *Arms* and *Bavg*. as expressed in (19). The electric and magnetic loading values are the target parameters specific to natural cooled PMSMs at this power level. The aspect ratio (*α=La/Dis*) gives the resultant dimensions. Finally, after the selection of capacitors, heat sink and other motor parameters, the basic objective function, the volumetric power density (*PDv*) of the system is determined using the height of each part and the machine outer diameter as shown in Fig. 2. Moreover, the active material volume and mass for copper, magnet and iron are also calculated.

|  |  |
| --- | --- |
|  | (19) |

3 System evaluation with design parameters

The variables in Table 2 are used to investigate the effect of each design parameter to the system performance indices such as overall system power density, drive and motor efficiency and active material mass.

Modül sayısını sub-sectionların içine yedirip birlikte yorumlayalım

3.1 The effect of switching frequency

Variation of motor drive efficiency with switching frequency is shown in Fig. 8 for different number of modules. Drive efficiency decreases as the switching frequency increases as expected, however this effect is more severe with low module numbers because the switching losses become more dominant than the conduction losses as the GaN current rating increases. Moreover, the relation with number of modules and efficiency is not linear because of

Switching frequency has no direct effect on Icrms



Figure 8. (a) Drive efficiency, (b) Required capacitance variation with switching frequency

3.2 The effect of modulation depth

Effect of ma on drive efficiency

Effect of ma on capacitance

Effect of ma on Icrms

Effect of ma



Figure 9. (a) Drive efficiency, (b) Required capacitance, (c) DC link current ripple, (d) motor efficiency variation with modulation depth

3.3 The effect of series connection

Number of series connected modules has no direct effect on Icrms



Figure 10. Capacitance requirement variation number of series and parallel connected modules



Heat sink volume değişimi

2seri-1paralel yapınca heat sink yetmiyor (90 kHz’ten sonra ısıyı atamıyor)



Capacitor and heat sink volume vs fsw together







Gridleri uçur

Online citation from mendeley

0-100kHz aralığında toplam hacmi ver

İki noktaya vurgu yapalım:

1. Multi-physics

2. Real components

Discrete nature of real components

Çelişkiler

Evrensel ilişkiler

Limitler (fsw şunun üstünde mantıklı değil, max 5 modül feasible gibi)

IMMD’ye özel ilişkiler

4 System design and simulation results

Your full paper should be submitted

Modellerin verification’ı ???

Analytical vs FEA % error ??? for verification

Add also efficiency vs output power

5 Conclusions

An 8kW, 540V DC link system is designed using the developed optimization tool.

The resultant system has the performance indices of x kW/lt, x % drive efficiency and y % motor efficiency

Acknowledgements

This work is partially supported by Scientific and Technological Research Council of Turkey (TUBITAK) under the TUBITAK project number 117E252.

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